SCES013F - JULY 1995 - REVISED JUNE 1999

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Output Ports Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

NOTE: For tape and reel order entry:

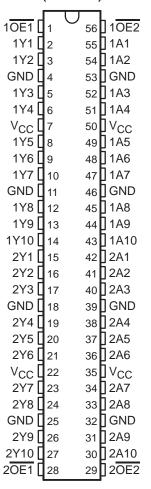
The DGGR package is abbreviated to GR, and the DGVR package is abbreviated to VR.

description

This 20-bit noninverting buffer/driver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH162827 is composed of two 10-bit sections with separate output-enable signals. For either 10-bit buffer section, the two output-enable (1OE1 and 1OE2 or 2OE1 and 2OE2) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer section are in the high-impedance state.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



The outputs, which are designed to sink up to 12 mA, include equivalent 26- Ω resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH162827 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

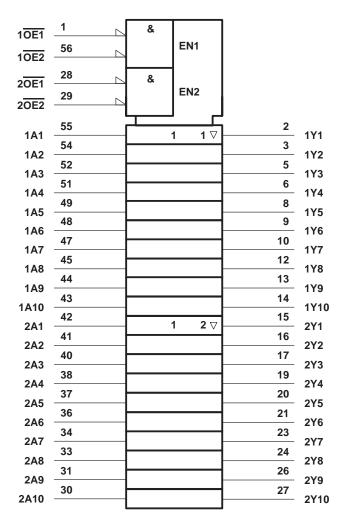
EPIC and Widebus are trademarks of Texas Instruments Incorporated.



FUNCTION TABLE (each 10-bit section)

INPUTS			OUTPUT
OE1	OE2	Α	Y
L	L	L	L
L	L	Н	Н
Н	X	Χ	Z
Х	Н	Χ	Z

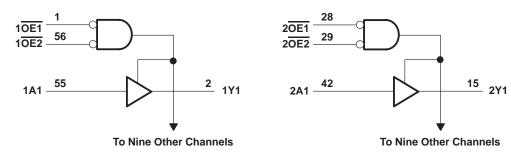
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)		–0.5 V to 4.6 V
Output voltage range, VO (see Notes 1 and 2)		. -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Continuous output current, IO		±50 mA
Continuous current through each V _{CC} or GND		±100 mA
Package thermal impedance, θ_{JA} (see Note 3):	DGG package	81°C/W
	DGV package	86°C/W
	DL package	74°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



SN74ALVCH162827 **20-BIT BUFFER/DRIVER** WITH 3-STATE OUTPUTS SCES013F - JULY 1995 - REVISED JUNE 1999

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		1.65	3.6	V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}			
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
٧ _I	Input voltage		0	Vcc	V	
٧o	Output voltage		0	Vcc	V	
		V _{CC} = 1.65 V		-2		
1	High-level output current	V _{CC} = 2.3 V		-6	A	
ЮН		V _{CC} = 2.7 V		-8	mA	
		V _{CC} = 3 V		-12		
		V _{CC} = 1.65 V		2		
la.	Low-level output current	V _{CC} = 2.3 V		6	m 1	
IOL		V _{CC} = 2.7 V		8	mA	
		V _{CC} = 3 V		12		
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCES013F - JULY 1995 - REVISED JUNE 1999

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CO	ONDITIONS	vcc	MIN	TYP [†]	MAX	UNIT	
		I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2			
		$I_{OH} = -2 \text{ mA}$		1.65 V	1.2				
		I _{OH} = -4 mA	2.3 V	1.9					
Vон		I 6 mA		2.3 V	1.7			V	
		IOH = -6 mA		3 V	2.4				
		I _{OH} = -8 mA		2.7 V	2				
		I _{OH} = -12 mA		3 V	2				
		I _{OL} = 100 μA		1.65 V to 3.6 V			0.2		
		$I_{OL} = 2 \text{ mA}$		1.65 V			0.45		
		I _{OL} = 4 mA		2.3 V			0.4		
VOL		lo. – 6 mA		2.3 V			0.55	V	
		I _{OL} = 6 mA		3 V			0.55		
		I _{OL} = 8 mA	2.7 V			0.6			
		I _{OL} = 12 mA	3 V			0.8			
Ц		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ	
		V _I = 0.58 V		1.65 V	25				
		V _I = 1.07 V		1.65 V	-25				
		V _I = 0.7 V		2.3 V	45				
I _{I(hold)}		V _I = 1.7 V		2.3 V	-45			μΑ	
		V _I = 0.8 V	V _I = 0.8 V		75				
		V _I = 2 V		3 V	-75				
		$V_{I} = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$		3.6 V			±500		
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
ICC		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
∆lcc		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ	
Ci	Control inputs	V _I = V _{CC} or GND		3.3 V		3.5		pF	
	Data inputs					6			
Co	Outputs	$V_O = V_{CC}$ or GND		3.3 V		7		pF	

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V	V _{CC} =	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(INFO1)	(001F01)	TYP MIN	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	А	Y	§	1	4.4		4.4	1.5	3.8	ns
t _{en}	ŌĒ	Υ	§	1.4	6.3		6.2	1.6	5.1	ns
^t dis	ŌĒ	Y	§	1.7	5.9		5.2	1.8	4.7	ns

[§] This information was not available at the time of publication.



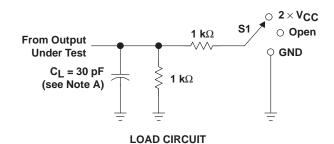
[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

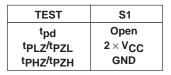
operating characteristics, T_A = 25°C

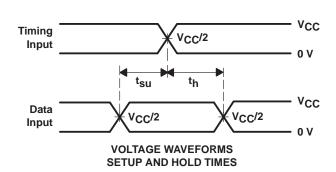
PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT	
		TEOT CONDITIONS	TYP	TYP	TYP	Olvili	
Power dissipation Out		Outputs enabled	C ₁ = 50 pF, f = 10 MHz	†	16	18	n.E
C _{pd} capacitance	Outputs disabled	CL = 50 pr, 1 = 10 MH2	†	4	6	p⊦	

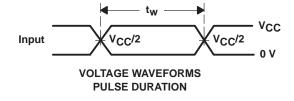
[†] This information was not available at the time of publication.

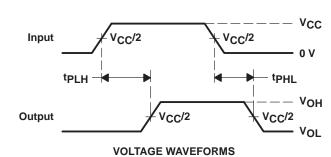
PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.8 V



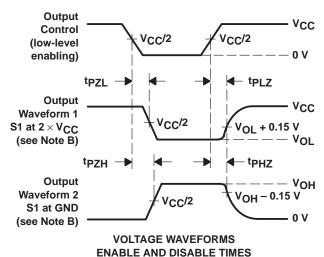








PROPAGATION DELAY TIMES



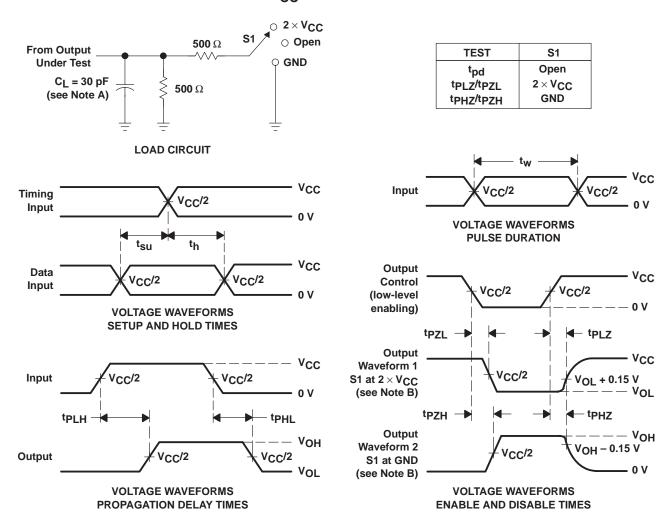
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

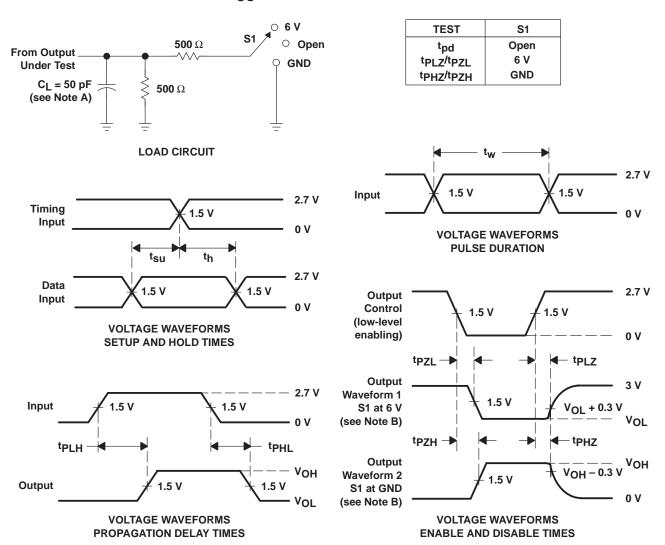


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \Omega$, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 $\Omega,\,t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1999, Texas Instruments Incorporated